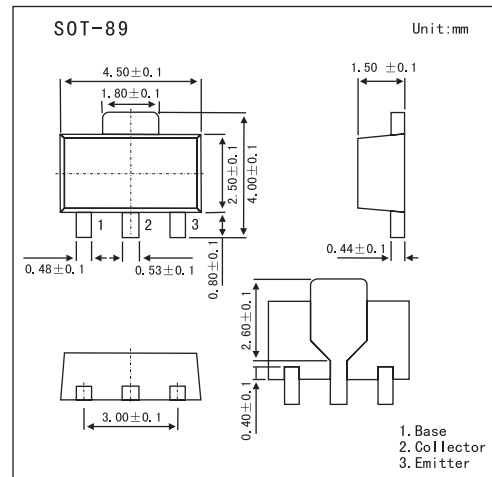


2SB1122

■ Features

- Adoption of FBET process..
- Very small size making it easy to provide highdensity hybrid IC's.



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Collector-base voltage	V _{CBO}	-60	V
Collector-emitter voltage	V _{CEO}	-50	V
Emitter-base voltage	V _{EBO}	-5	V
Collector current	I _C	-1	A
Collector current (pulse)	I _{CP}	-2	A
Collector dissipation	P _C	500	mW
Jumction temperature	T _J	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit
Collector cutoff current	ICBO	V _{CB} = -50V, I _E = 0			-100	nA
Emitter cutoff current	IEBO	V _{CB} = -4V, I _E = 0			-100	nA
DC current Gain	hFE	V _{CE} = -2V, I _C = -100mA	100		560	
Gain bandwidth product	f _T	V _{CE} = -10V, I _C = -50mA		150		MHz
Output capacitance	C _{ob}	V _{CB} = -10V, f = 1MHz		12		pF
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = -500mA, I _B = -50mA		-180	-500	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C = -500mA, I _B = -50mA		-0.9	-1.2	V
Collector-base breakdown voltage	V _{(BR)CBO}	I _C = -10μA, I _E = 0	-60			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C = -1mA, R _{BE} = ∞	-50			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E = -10μA, I _C = 0	-5			V
Turn-on time	ton	<p>IC = 10mA IB1 = -10mA IB2 = 500mA</p>		40		ns
Storage time	tstg			300		ns
Fall time	tf			30		ns

■ hFE Classification

Marking	BE			
	R	S	T	U
hFE	100~200	140~280	200~400	280~560